

REMARKS

The foregoing Amendment and remarks which follow are responsive to the Office Action mailed October 8, 2003 in relation to the above-identified patent application. In that Office Action, the Examiner rejected Claims 1, 5, 7 and 19 under 35 U.S.C. §102(b) as being anticipated by the Pavio reference. Additionally, the Examiner rejected Claims 1, 4, 6, 7, 13 and 18 under 35 U.S.C. §102(e) as being anticipated by the Carter, Jr. et al reference, and rejected Claims 6 and 17 under 35 U.S.C. §103(a) as being unpatentable over the combination of the Carter, Jr. et al and Sharma et al references. Finally, Claim 20 was rejected under Section 103(a) as being unpatentable over the combination of the Pavio and Sharma et al references.

Importantly, the Examiner indicated that Claims 14 and 21 were objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all the limitations of the base claim and any intervening claims.

By this Amendment, Applicant has cancelled objected to Claim 14, and has incorporated the limitations originally recited therein into base independent Claim 13. Due to Claim 14 only having been objected to by the Examiner, Applicant respectfully submits that independent Claim 13 as currently amended is now in condition for allowance, as are Claims 17 and 18 as being dependent upon an allowable base claim. Additionally, Applicant has cancelled objected to Claim 21 and intervening Claim 20, and incorporated the limitations originally recited therein into base independent Claim 19. Due to Claim 21 also only having been objected to by the Examiner, Applicant respectfully submits that independent Claim 19 as currently amended is also now in condition for allowance. Claims 22, 23 and 25 have been amended only to change their dependency to Claim 19, and are believed to be in condition for allowance as being dependent upon an allowable base claim.

In addition to the foregoing, Applicant has cancelled Claim 7, and amended independent Claim 1 to describe the upper surfaces of the leads as residing on a common plane which extends between the upper and lower surfaces of the chip paddle, and further to describe at least portions of the lower surfaces of the chip paddle and the leads as being externally exposed in a common exterior surface of the package body. Applicant respectfully submits that independent Claim 1 is not anticipated by the teachings of either the Pavio or

Carter, Jr. et al references cited in the subject Office Action in support of the Section 102(b) and Section 102(e) rejections, respectively, thereof.

As is best seen in Figure 3 thereof, the Pavio reference discloses a leadframe 10 including a semiconductor die mounting area 12 having a semiconductor die 30 mounted thereto. In addition to the mounting area 12, the leadframe 10 includes bonding pads 26, 27 which are positioned on opposing sides of the mounting area 12. Though the thickness of each of the bonding pads 26, 27 is less than that of the mounting area 12, there is no teaching or suggestion in the Pavio reference of the lower surfaces of the bonding pads 26, 27 and the lower surface of the mounting area 12 being externally exposed in a common exterior surface of the surrounding package body. Nor is there any teaching or suggestion regarding the upper surfaces of the bonding pads 26, 27 residing on a common plane which extends between the upper and lower surfaces of the mounting area 12. Rather, as is clearly shown in Figure 3 of the Pavio reference, the upper surfaces of the bonding pads 26, 27 extend in coplanar relation to the upper surface of the mounting area 12.

Like the Pavio reference, the Carter, Jr. et al reference fails to teach or suggest the upper surfaces of the leads 203 of the semiconductor package described therein as residing on a common plane which extends between the upper and lower surfaces of the die mount pad 201 of the semiconductor package leadframe. Rather, as is clearly shown in Figures 2a, 4a, 4b and 6 of the Carter, Jr. et al reference, portions of the top surfaces of each of the leads 203 are actually disposed or elevated well above the top surface 201a of the die mount pad 201, and thus do not reside on a common plane which extends between the upper and lower surfaces 201a, 201b of the die mount pad 201. Thus, Applicant respectfully submits that independent Claim 1 as amended is in condition for allowance, as are Claims 4-6 as being dependent upon an allowable base claim.

On the basis of the foregoing, Applicant respectfully submits that the stated grounds of rejection have been overcome, and that Claims 1, 4-6, 13, 17-19, 22, 23 and 25 are now in condition for allowance. An early Notice of Allowance is therefore respectfully requested.

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If any additional fee is required, please charge Deposit Account Number 19-4330.

Respectfully submitted,

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